

AUG 20 2008

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Applicant:	§	Art Unit:	1792
Michael L. McSwiney et al.	§		
Serial No.:	§	Examiner:	David P. Turocy
10/764,193	§		
Filed:	§	Atty Docket:	ITL.1056US P17793
January 23, 2004	§		
For:	§	Assignee:	Intel Corporation
Forming a Silicon Nitride Film	§		

OK TO ENTER: /D.T./

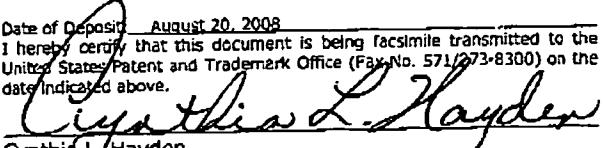
Mail Stop AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

08/25/2008

REPLY TO FINAL REJECTION

Sir:

In response to the final rejection mailed July 18, 2008, please amend the above-referenced patent application as follows:

Date of Deposit: August 20, 2008
I hereby certify that this document is being facsimile transmitted to the United States Patent and Trademark Office (Fax No. 571/273-8300) on the date indicated above.

Cynthia L. Hayden